IPC-9262

组装行业应用之AOI设备的特性描述与鉴定

Specification for Characterization and Verification of Assembly Level Automatic Optical Inspection Equipment

这份双语的IPC国际标准是由自动光学检测设备的特性描述与鉴定小组委员会(7-32CN)以母语中文开发并翻译成英语，经由同行审查后出版。如中文和英语之间有冲突，以中文优先。

This dual-language IPC international standard was developed by the Automatic Optical Inspection Characterization and Verification Subcommittee (7-32CN) in its native language and was translated to English for peer review and publication. In the event of conflict between Mandarin and English, Mandarin will take precedence.

鼓励本标准的使用者参加未来修订版的开发。

Users of this standard are encouraged to participate in the development of future revisions.

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1 范围

本标准提供AOI（Automatic Optical Inspection）设备及其重要特性与参数的相关定义, 鉴定方法和要求； 透过本标准可以使AOI设备的生产厂商提供一致的设备特性描述；及提供AOI使用者验收及允收的参考依据。

1 SCOPE

This standard (specification) provides relevant definition, testing, certification and requirements of automatic optical inspection (AOI) equipment and its significant characteristics and parameters. AOI equipment manufacturers can use this specification to provide consistent equipment characteristic description, and AOI users can use it as a reference of certification and acceptance for AOI.

1.1 目的 本标准制定的目的在于建立AOI设备中对于其设备检测效能有重要影响的部件及整机之重要特性及参数进行文字定义及测试和鉴定方法; 另外对使用者提供应用量测系统分析对AOI设备的验收方法及允收标准。

1.1 Purpose This standard (specification) is formulated for establishing wording and definition and testing and certification method of the key features and parameters of the components and complete machine, which has important influence on the equipment testing efficiency in AOI equipment. It also provides users with measurement system analysis for acceptance methods and acceptability criteria of the AOI equipment.

2 适用文件

下列列出各机构所发行的文件, 规范或标准被引用及被应用于本规范中。

2 APPLICABLE DOCUMENTS

The following documents of the issue in effect at the time of the order form a part of this specification to the extent specified herein.

2.1 IPC[1]

IPC-T-50 电子电路互连与封装名词术语及定义 (Terms and Definitions for Interconnecting and Packaging Electronic Circuits)

IPC-OI-645 Standard for Visual Optical Inspection Aids

IPC-A-610F 电子组件的可接受性 (Acceptability of Electronic Assemblies)

IPC-9850 Surface Mount Placement Equipment Characterization

2.2 Automotive Industry Action Group (AIAG)[2]

TS16949 MSA测量系统分析手册 (Measurement System Analysis (MSA))

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[1] www.ipc.org

[2] www.aiag.org